

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**priority** Application Serial No. . . . . 09/389,844  
**priority** Filing Date . . . . . September 2, 1999  
Inventor . . . . . Salman Akram  
Assignee . . . . . Micron Technology, Inc.  
**priority** Group Art Unit . . . . . 2826  
**priority** Examiner . . . . . F. Abraham  
Attorney's Docket No. . . . . MI22-1572  
Title: Methods Of Forming Board-On-Chip Packages (as amended)

## **PRELIMINARY AMENDMENT**

To: BOX NON-FEE AMENDMENT  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: David G. Latwesen, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)  
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## AMENDMENTS

## In the Specification

Replace the title with,

--Methods Of Forming Board-On-Chip Packages--

At p. 1, before the “Technical Field” section, insert

## --RELATED PATENT DATA

This patent resulted from a divisional application of U.S. Patent Application Serial No. 09/389,844, which was filed on September 2, 1999.--.

## Amended Claims

Cancel claims 1-41.

**REMARKS**

Claims 1-41 are canceled, leaving claims 42-74 pending in the application. Applicant requests substantive examination of pending claims 42-74 in the Examiner's next Action.

Respectfully submitted,

By:

  
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Reg. No. 38,533

Dated: January 9, 2001